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24319 7590 03/09/2004
LSI LOGIC CORPORATION
1621 BARBER LANE
MS: D-106 LEGAL
MILPITAS, CA 95035

EXAMINER	
KOBERT, RUSSELL MARC	
ART UNIT	PAPER NUMBER
2829	
DATE MAILED: 03/09/2004	

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/981,200	10/17/2001	Brad Johnson	01-724	5763

TITLE OF INVENTION: VORTEX UNIT FOR PROVIDING A DESIRED ENVIRONMENT FOR A SEMICONDUCTOR PROCESS

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1330	\$0	\$1330	06/09/2004

THE APPLICATION IDENTIFIED ABOVE HAS BEEN EXAMINED AND IS ALLOWED FOR ISSUANCE AS A PATENT. **PROSECUTION ON THE MERITS IS CLOSED.** THIS NOTICE OF ALLOWANCE IS NOT A GRANT OF PATENT RIGHTS. THIS APPLICATION IS SUBJECT TO WITHDRAWAL FROM ISSUE AT THE INITIATIVE OF THE OFFICE OR UPON PETITION BY THE APPLICANT. SEE 37 CFR 1.313 AND MPEP 1308.

THE ISSUE FEE AND PUBLICATION FEE (IF REQUIRED) MUST BE PAID WITHIN **THREE MONTHS** FROM THE MAILING DATE OF THIS NOTICE OR THIS APPLICATION SHALL BE REGARDED AS ABANDONED. **THIS STATUTORY PERIOD CANNOT BE EXTENDED.** SEE 35 U.S.C. 151. THE ISSUE FEE DUE INDICATED ABOVE REFLECTS A CREDIT FOR ANY PREVIOUSLY PAID ISSUE FEE APPLIED IN THIS APPLICATION. THE PTOL-85B (OR AN EQUIVALENT) MUST BE RETURNED WITHIN THIS PERIOD EVEN IF NO FEE IS DUE OR THE APPLICATION WILL BE REGARDED AS ABANDONED.

HOW TO REPLY TO THIS NOTICE:

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If the SMALL ENTITY is shown as YES, verify your current SMALL ENTITY status:

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B. If applicant claimed SMALL ENTITY status before, or is now claiming SMALL ENTITY status, check the box below and enclose the PUBLICATION FEE and 1/2 the ISSUE FEE shown above.

☐ Applicant claims SMALL ENTITY status.
See 37 CFR 1.27.

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III. All communications regarding this application must give the application number. Please direct all communications prior to issuance to Mail Stop ISSUE FEE unless advised to the contrary.

IMPORTANT REMINDER: Utility patents issuing on applications filed on or after Dec. 12, 1980 may require payment of maintenance fees. It is patentee's responsibility to ensure timely payment of maintenance fees when due.

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Complete and send this form, together with applicable fee(s), to: **Mail**

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I hereby certify that this Fee(s) Transmittal is being deposited with the United States Postal Service with sufficient postage for first class mail in an envelope addressed to the "Mail Stop ISSUE FEE" address above, or being facsimile transmitted to the USPTO, on the date indicated below.

(Depositor's name)
(Signature)
(Date)

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nonprovisional	NO	\$1330	\$0	\$1330	06/09/2004

EXAMINER	ART UNIT	CLASS-SUBCLASS
KOBERT, RUSSELL MARC	2829	324-760000

1. Change of correspondence address or indication of "Fee Address" (37 CFR 1.363).

- ☐ Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached.
- ☐ "Fee Address" indication (or "Fee Address" Indication form PTO/SB/47; Rev 03-02 or more recent) attached. Use of a Customer Number is required.

2. For printing on the patent front page, list (1) the names of up to 3 registered patent attorneys or agents OR, alternatively, (2) the name of a single firm (having as a member a registered attorney or agent) and the names of up to 2 registered patent attorneys or agents. If no name is listed, no name will be printed.

1	_____
2	_____
3	_____

3. ASSIGNEE NAME AND RESIDENCE DATA TO BE PRINTED ON THE PATENT (print or type)

PLEASE NOTE: Unless an assignee is identified below, no assignee data will appear on the patent. Inclusion of assignee data is only appropriate when an assignment has been previously submitted to the USPTO or is being submitted under separate cover. Completion of this form is NOT a substitute for filing an assignment.

(A) NAME OF ASSIGNEE

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Please check the appropriate assignee category or categories (will not be printed on the patent); ☐ individual ☐ corporation or other private group entity ☐ government

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This collection of information is required by 37 CFR 1.311. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, Alexandria, Virginia 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Alexandria, Virginia 22313-1450.

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EXAMINER

KOBERT, RUSSELL MARC

ART UNIT

PAPER NUMBER

2829

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Determination of Patent Term Adjustment under 35 U.S.C. 154 (b) (application filed on or after May 29, 2000)

The Patent Term Adjustment to date is 225 day(s). If the issue fee is paid on the date that is three months after the mailing date of this notice and the patent issues on the Tuesday before the date that is 28 weeks (six and a half months) after the mailing date of this notice, the Patent Term Adjustment will be 225 day(s).

If a Continued Prosecution Application (CPA) was filed in the above-identified application, the filing date that determines Patent Term Adjustment is the filing date of the most recent CPA.

Applicant will be able to obtain more detailed information by accessing the Patent Application Information Retrieval (PAIR) system (<http://pair.uspto.gov>).

Any questions regarding the Patent Term Extension or Adjustment determination should be directed to the Office of Patent Legal Administration at (703) 305-1383. Questions relating to issue and publication fee payments should be directed to the Customer Service Center of the Office of Patent Publication at (703) 305-8283.

Notice of Allowability

Application No.

09/981,200

Examiner

Russell M Kobert

Applicant(s)

JOHNSON, BRAD

Art Unit

2829

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. **THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS.** This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.

1. ☒ This communication is responsive to the Amendment filed February 26, 2004.
2. ☒ The allowed claim(s) is/are 1-4, 6-12, 14-17, 19-22, 24, 25 and 27.
3. ☒ The drawings filed on 17 October 2001 are accepted by the Examiner.
4. ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 - a) ☐ All b) ☐ Some* c) ☐ None of the:
 1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

* Certified copies not received: _____.

Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.
THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.

5. ☐ A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.
6. ☐ CORRECTED DRAWINGS (as "replacement sheets") must be submitted.
 - (a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached
 - 1) ☐ hereto or 2) ☐ to Paper No./Mail Date _____.
 - (b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date _____.

Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).
7. ☐ DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.

Attachment(s)

- | | |
|---|--|
| 1. <input type="checkbox"/> Notice of References Cited (PTO-892) | 5. <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 2. <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 6. <input type="checkbox"/> Interview Summary (PTO-413),
Paper No./Mail Date _____. |
| 3. <input type="checkbox"/> Information Disclosure Statements (PTO-1449 or PTO/SB/08),
Paper No./Mail Date _____ | 7. <input type="checkbox"/> Examiner's Amendment/Comment |
| 4. <input type="checkbox"/> Examiner's Comment Regarding Requirement for Deposit
of Biological Material | 8. <input type="checkbox"/> Examiner's Statement of Reasons for Allowance |
| | 9. <input type="checkbox"/> Other _____ |

David A. Zamecke
Primary Examiner
3/3/14

Image *AP*
2829



Docket No. 01-724

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of : Johnson, Brad
Serial No. : 09/981,200
Examiner : Kobert, Russell Marc
Art Unit : 2829
Filed : October 17, 2001
For : VORTEX UNIT FOR PROVIDING A DESIRED
ENVIRONMENT FOR A SEMICONDUCTOR PROCESS

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Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE TO OFFICE ACTION
DATED DECEMBER 30, 2003**

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. § 1.8)

I hereby certify that, on the date shown below, this correspondence is being:

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☒ [X] deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

☐ [] transmitted by facsimile to the Patent and Trademark Office.

Michele D. Norine
Michele D. Norine

DATED: February 18, 2004

Dear Sir:

This is in response to the Office Action dated December 30, 2003, for which the three-month shortened statutory period is set to expire on March 30, 2003. While Applicant believes that no extension of time for response is necessary, should the Office determine that any additional fees are necessary for this response, the Commissioner is hereby authorized to charge any deficiencies to Deposit Account No. 12-2252.

Appl. No. 09/981,200
Response to Office Action mailed December 30, 2003

Amendment to the Claims are reflected in the **Listing of Claims** which begins on page 3 of this paper.

Remarks/Arguments begin on page 9 of this paper.

Amendment to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A vortex unit suitable for providing a desired environment for a semiconductor process, comprising:

a vortex tube having an air inlet for receiving compressed air, a first air exhaust for outputting an air stream having a temperature greater than the received compressed air, and a second air exhaust for outputting an air stream having a temperature lower than the received compressed air; and

a semiconductor processing device suitable for performing a semiconductor processing function, wherein the semiconductor processing device is connected to the second air exhaust of the vortex tube so that the semiconductor processing device receives a cooled air stream from the vortex tube, the cooled air stream providing an environment suitable for enabling the semiconductor processing device to perform the semiconductor processing function while being exposed to the desired environment; and

a manifold disposed between the vortex tube and the semiconductor processing device, wherein the manifold is operably connected to the second air exhaust of the vortex tube, and includes a plurality of tubes for ducting air received by the manifold to more than one location on the semiconductor processing device.

2. (Original) The vortex unit as described in claim 1, wherein the environment is approximately 25 degrees Celsius.

3. (Original) The vortex unit as described in claim 1, wherein the semiconductor processing device includes a testing device for testing operation of a semiconductor.

4. (Original) The vortex unit as described in claim 3, wherein the semiconductor is a wafer.

5. (Canceled)

6. (Original) The vortex unit as described in claim 1, wherein the cooled air stream is directed to a platen area of a prober of the semiconductor processing device.

7. (Original) The vortex unit as described in claim 1, wherein the cooled air stream is directed to a chuck top of a prober.

8. (Original) The vortex unit as described in claim 7, wherein a wafer to be tested by the prober is cooled by the cooled prober.

9. (Original) The vortex unit as described in claim 1, wherein the first air exhaust is ducted so as not to interfere with the semiconductor processing device.

10. (Currently Amended) A vortex unit suitable for providing a desired environment for a testing a semiconductor device, comprising:

a vortex tube having an air inlet for receiving compressed air, a first air exhaust for outputting an air stream having a temperature greater than the received compressed air, and a second air exhaust for outputting an air stream having a temperature lower than the received compressed air; ~~and~~

a semiconductor testing device suitable for testing at least one function of a semiconductor device, wherein the semiconductor testing device is connected to the second air exhaust of the vortex tube so that the semiconductor testing device receives a cooled air stream from the vortex tube, the cooled air stream cooling a semiconductor device to a desired testing temperature enabling the semiconductor testing device to test the at least one function of the semiconductor device at the desired temperature; and

a manifold disposed between the vortex tube and the semiconductor testing device, wherein the manifold is operably connected to the second air exhaust of the vortex tube, and includes a plurality of tubes for ducting air received by the manifold to more than one location on the semiconductor testing device.

11. (Original) The vortex unit as described in claim 10, wherein the temperature is approximately 25 degrees Celsius.

12. (Original) The vortex unit as described in claim 10, wherein the semiconductor is a wafer.

13. (Canceled)

14. (Original) The vortex unit as described in claim 10, wherein the cooled air stream is directed to a platen area of a prober of the semiconductor testing device.

15. (Original) The vortex unit as described in claim 10, wherein the cooled air stream is directed to a chuck top of a prober.

16. (Original) The vortex unit as described in claim 15, wherein a wafer to be tested by the prober is cooled by the cooled prober.

17. (Currently Amended) A vortex unit suitable for providing a desired environment for testing a semiconductor, comprising:

a means for providing a vortex having an air inlet for receiving compressed air, a first air exhaust for outputting an air stream having a temperature greater than the received compressed air, and a second air exhaust for outputting an air stream having a temperature lower than the received compressed air; and

a means for testing a semiconductor device, wherein the semiconductor testing means is connected to the second air exhaust of the vortex means so that the

semiconductor testing means receives a cooled air stream from the vortex means, the cooled air stream providing an environment suitable for enabling the semiconductor testing means to perform a semiconductor testing function; and

a manifold disposed between the vortex means and the semiconductor testing means, wherein the manifold is operably connected to the second air exhaust of the vortex means, and includes a plurality of tubes for ducting air received by the manifold to more than one location on the semiconductor testing means.

18. (Canceled)

19. (Original) The vortex unit as described in claim 17, wherein the cooled air stream is directed to a platen area of a means for probing of the semiconductor testing means.

20. (Original) The vortex unit as described in claim 17, wherein the cooled air stream is directed to a chuck top of the probing means.

21. (Currently Amended) A semiconductor processing apparatus suitable for providing a desired environment for a semiconductor process, comprising:

a vortex tube having an air inlet for receiving compressed air, a first air exhaust for outputting an air stream having a temperature greater than the received compressed air, and a second air exhaust for outputting an air stream having a temperature lower than the received compressed air; and

a semiconductor processing device suitable for performing a semiconductor processing function, wherein the semiconductor processing device is connected to the second air exhaust of the vortex tube so that the semiconductor processing device receives a cooled air stream from the vortex tube, the cooled air stream providing an environment suitable for enabling the semiconductor processing device to perform the semiconductor processing function while being exposed to the desired environment; and
a manifold disposed between the vortex tube and the semiconductor processing

device, wherein the manifold is operably connected to the second air exhaust of the vortex tube, and includes a plurality of tubes for ducting air received by the manifold to more than one location on the semiconductor processing device.

22. (Previously Presented) The semiconductor processing apparatus of Claim 21, wherein the semiconductor processing device is a wafer sort machine.

23. (Canceled)

24. (Currently Amended) The semiconductor processing apparatus of Claim 21 [[23]], wherein the manifold aforementioned is a first manifold, further comprising a second manifold linking the first and second air exhausts to provide a range of hot and cold temperature in the semiconductor processing device.

25. (Currently Amended) A semiconductor testing apparatus suitable for providing a desired environment for a testing a semiconductor device, comprising:

a vortex tube having an air inlet for receiving compressed air, a first air exhaust for outputting an air stream having a temperature greater than the received compressed air, and a second air exhaust for outputting an air stream having a temperature lower than the received compressed air; and

a semiconductor testing device suitable for testing at least one function of a semiconductor device, wherein the semiconductor testing device is connected to the second air exhaust of the vortex tube so that the semiconductor testing device receives a cooled air stream from the vortex tube, the cooled air stream cooling a semiconductor device to a desired testing temperature enabling the semiconductor testing device to test at least one function of the semiconductor device at the desired temperature; and

a manifold disposed between the vortex tube and the semiconductor processing device, wherein the manifold is operably connected to the second air exhaust of the vortex tube, and includes a plurality of tubes for ducting air received by the manifold to more than one location on the semiconductor testing device.

26. (Canceled)

27. (Currently Amended) The semiconductor testing apparatus of Claim 25 [[26]], wherein the manifold aforementioned is a first manifold, further comprising a second manifold linking the first and second air exhausts to provide a range of hot and cold temperature in the semiconductor testing device.

REMARKS

Claims 1-4, 6-12, 14-17, 19-22, 24-25 and 27 are pending. Claims 1, 10, 17, 21, 24, 25 and 27 have been amended. Claims 5, 13, 18, 23 and 26 have been canceled.

Claim Rejections – 35 U.S.C. § 102(b)

The Patent Office rejected Claims 1-4, 6-12, 14-17, 19-22 and 25 under 35 U.S.C. 102(b) as being clearly anticipated by Amemiya, U.S. Patent No. 6,249,132.

The Patent Office rejected Claims 1-4, 6-12, 14-17, 19-22 and 25 under 35 U.S.C. 102(b) as being clearly anticipated by Peters, U.S. Patent No. 4,848,090.

Allowable Subject Matter

The Patent Office indicated claims 5, 13, 18, 23, 24, 26 and 27 would be allowable is rewritten in independent form including all the limitations of the base claim and any intervening claims.

Claims 1, 10, 17, 21 and 25 have been amended to include the limitations of claims 5, 13, 18, 23 and 26 respectively, consequently, claims 1-4, 6-12, 14-17, 19-22, 24-25 and 27 are believed allowable.

CONCLUSION

In light of the forgoing amendments and arguments, reconsideration of the claims is hereby requested, and a Notice of Allowance is earnestly solicited.

Respectfully submitted,

DATED: February 18, 2004

A handwritten signature in black ink, appearing to read "Chad W. Swantz", written over a horizontal line.

Attorney for Applicant
Chad W. Swantz
Reg. No. 46,329

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